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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/807,262	03/24/2004	Kazuhiko Fukazawa	119216	3894

25944 7590 01/13/2006

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EXAMINER

NGUYEN, JIMMY

ART UNIT	PAPER NUMBER
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2829

DATE MAILED: 01/13/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No. 10/807,262	Applicant(s) FUKAZAWA ET AL.	
	Examiner Jimmy Nguyen	Art Unit 2829	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 25 October 2005.
- 2a) ☐ This action is FINAL. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-17 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-17 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 06 December 2004 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All b) ☐ Some * c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

Response to Argument

The examiner acknowledges the amendment filed 10/25/05 with the following effect;

Applicant's arguments with respect to claims 1- 17 have been considered but are moot in view of the new ground(s) of rejection.

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

2. Claims 1 –17 are rejected under 35 U.S.C. 102(e) as being anticipated by Sandland et al (US 4,644,172).

As to claims 1, 8, 15, Sandland et al disclose (fig 2) a substrate inspection system and method comprising:

a first inspection (macro inspection, column 6 line 36) apparatus executing a macro inspection of each of a plurality of substrates (16) and outputting information (to computer 56) on presence/absence of a defect on each of the substrates (16),

a storage unit (48) storing therein for each of the substrates (16) the information on presence/absence of a defect outputted from said first inspection apparatus, and

a second inspection (micro inspection, column 6 line 36 -40) apparatus executing an inspection of a predetermined portion of the substrate, wherein

said second inspection apparatus (micro inspection) refers to the information on presence/absence of a defect stored in said storage unit (48) and executes the inspection of substrates of the plurality of substrates, the substrates being one that does/do not have the defect.

As to claims 2, 9, Sandland et al disclose (fig 2) the substrate inspection system and method according to claims 1 ,8, wherein said second inspection (micro inspection) apparatus executes the inspection by measuring a relative offset between a resist pattern formed on a surface of the substrate and an underlying pattern.

As to claims 3, 10, 16, Sandland et al disclose (fig 2) a substrate inspection system and method comprising :

a first inspection apparatus (macro inspection) executing a macro inspection of each of a plurality of substrates (16) and outputting information on distribution of a defect on each of the substrates,

a storage unit (48) storing therein for each of the substrates the information on distribution of a defect outputted from said first inspection apparatus; and

a second inspection apparatus (micro inspection) executing an inspection of a predetermined portion of the substrate, wherein

said second inspection apparatus (micro inspection) refers to the information on distribution of a defect stored in said storage unit (48) and executes the inspection of substrates of the plurality of substrates, the substrates being one that does/do not have the defect distributed in the predetermined portion.

As to claims 4, 11, Sandland et al disclose (fig 2) the substrate inspection system and method according to claims 3,10, wherein said second inspection apparatus (micro inspection) executes the inspection by measuring a relative offset between a resist pattern formed on a surface of the substrate and an underlying pattern.

As to claims 5, 12, 17, Sandland et al disclose (fig 2) a substrate inspection system and method comprising:

a first inspection (macro inspection) apparatus executing a macro inspection of each of a plurality of substrates and outputting information on distribution and classification of a defect on each of the substrates,

a storage unit (48) storing therein for each of the substrates the information on distribution and classification of a defect outputted from said first inspection (macro inspection) apparatus, and

a second inspection apparatus (micro inspection) executing an inspection of a predetermined portion of the substrate, wherein

said second inspection apparatus (micro inspection) refers to the information on distribution and classification of a defect stored in said storage unit and determines substrates to be inspected from the plurality of substrates.

As to claims 6, 13, Sandland et al disclose (fig 2) the substrate inspection system and method according to claims 5, 12, wherein said second inspection apparatus (micro inspection) determines substrates to be inspected according to how much a kind of the defect contained in the classification information is associated with a kind of a defect detectable by said second inspection apparatus.

As to claims 7, 14, Sandland et al disclose (fig 2) the substrate inspection system and method according to claims 5, 12, wherein said second inspection apparatus (micro inspection) executes the inspection by measuring a line width of a resist pattern formed on a surface of the substrate.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jimmy Nguyen whose telephone number is 571-272-1965. The examiner can normally be reached on M-F from 9 to 5.

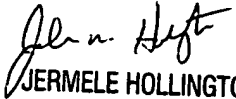
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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Ramtez Nestor , can be reached on 571-272-2034. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Jimmy Nguyen

1/5/06


JERMELE HOLLINGTON
PRIMARY EXAMINER
A02829
01/09/06